

## 30V N-Channel Enhancement Mode MOSFET

### Description

The AP30N03DF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

### General Features

$V_{DS} = 30V$   $I_D = 30A$

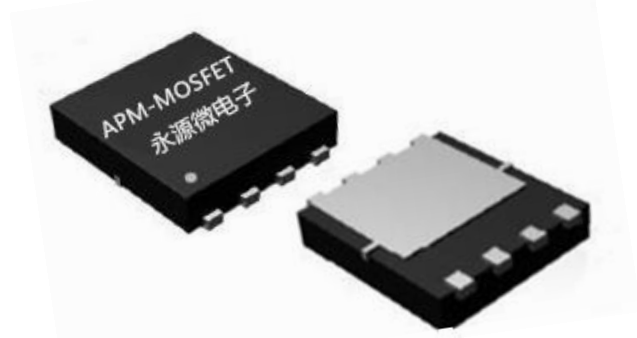
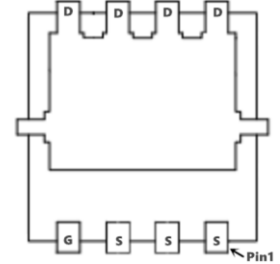
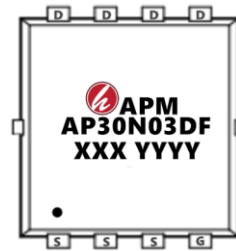
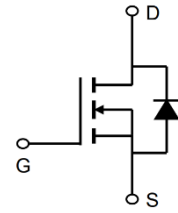
$R_{DS(ON)} < 25m\Omega$  @  $V_{GS}=10V$  (Type:  $15m\Omega$ )

### Application

Battery protection

Load switch

Uninterruptible power supply



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP30N03DF	PDFN3*3-8L	AP30N03D XXX YYYY	5000

### Absolute Maximum Ratings ( $T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	30	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	12	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	50	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	8.1	mJ
$I_{AS}$	Avalanche Current	12.7	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation <sup>4</sup>	20.8	W
$P_D@T_A=25^{\circ}C$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	62	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	6	$^{\circ}C/W$

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### Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	32	---	V
ΔBVDSS/ΔT <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.023	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	---	15.6	25	mΩ
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A	---	28.5	38	mΩ
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.6	2.5	V
ΔVGS(th)	VGS(th) Temperature Coefficient		---	-4.2	---	mV/°C
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =10A	---	5.5	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	2.3	---	Ω
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	---	4.9	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.66	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	1.85	---	
Td(on)	Turn-On Delay Time	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V R <sub>G</sub> =3.3Ω I <sub>D</sub> =10A	---	1.6	---	ns
T <sub>r</sub>	Rise Time		---	15.8	---	
Td(off)	Turn-Off Delay Time		---	13	---	
T <sub>f</sub>	Fall Time		---	4.8	---	
Ciss	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	---	216	---	pF
Coss	Output Capacitance		---	62	---	
Crss	Reverse Transfer Capacitance		---	51	---	
IS	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	24	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	50	A
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.2	V
trr	Reverse Recovery Time	IF=10A, dI/dt=100A/μs, T <sub>J</sub> =25°C	---	8.7	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	1.95	---	nC

#### Note :

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The test condition is V<sub>GS</sub>≅ 300us , duty cycle DD=25≅V, V<sub>GS</sub>=10V, L=0.1mH, IAS=12.7A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

### Typical Characteristics

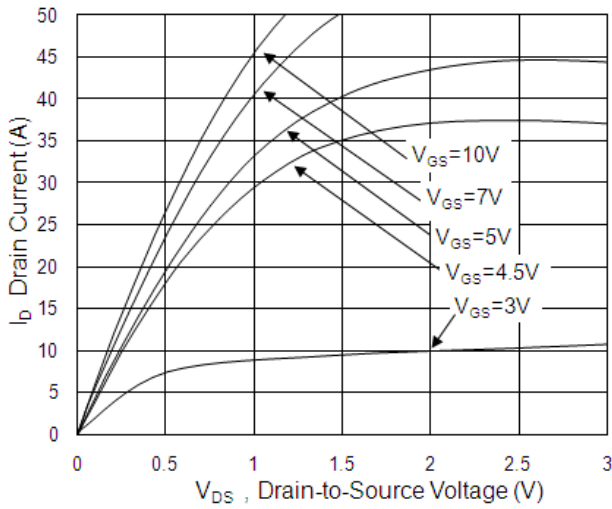


Fig.1 Typical Output Characteristics

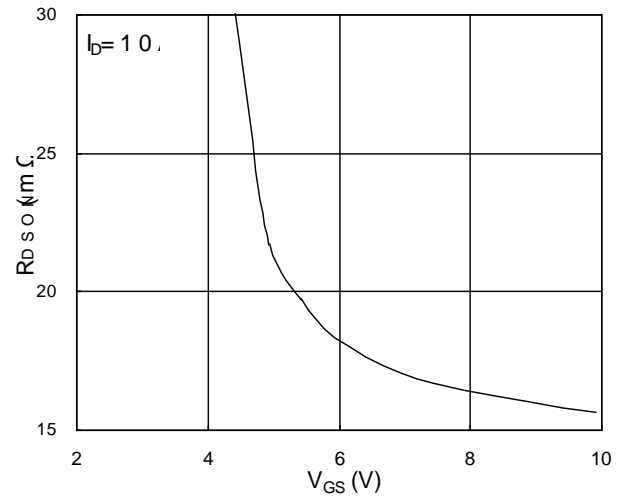


Fig.2 On-Resistance vs. Gate-Source

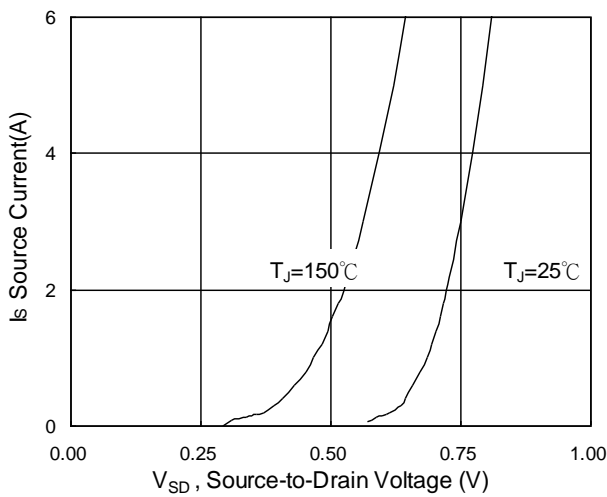


Fig.3 Forward Characteristics Of Reverse

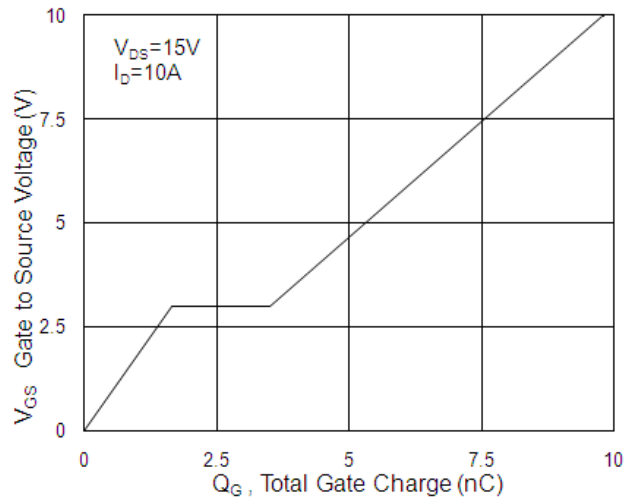


Fig.4 Gate-Charge Characteristics

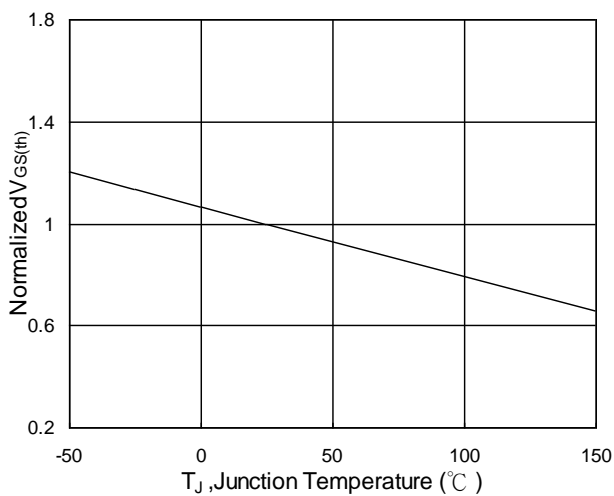


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

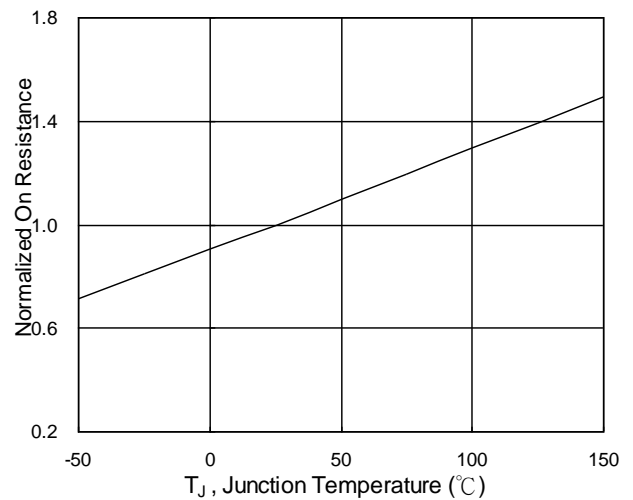
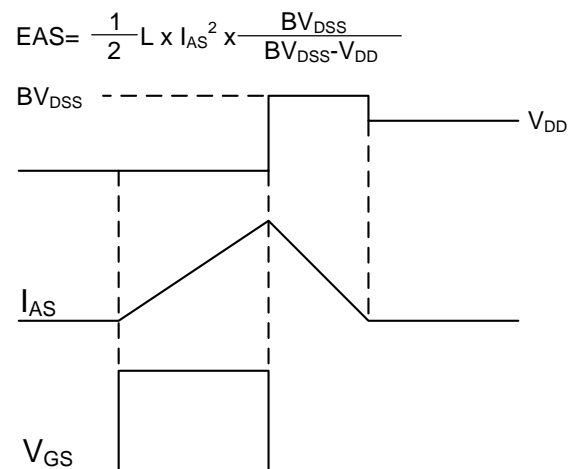
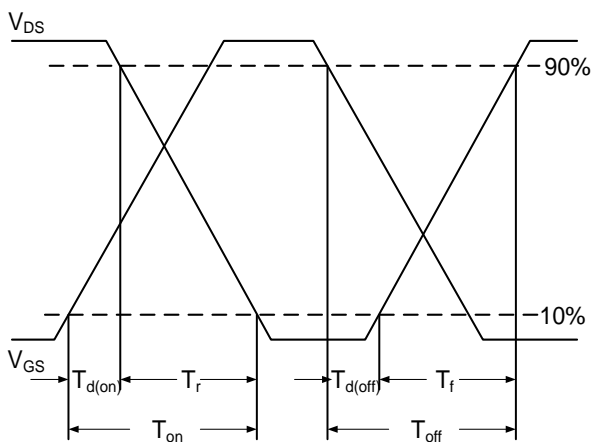
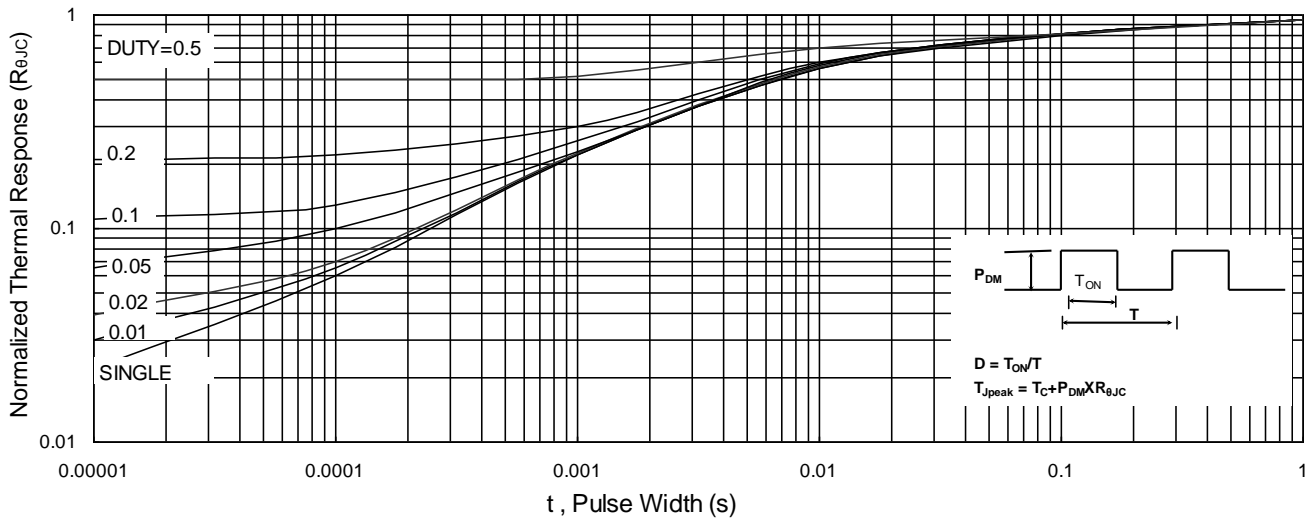
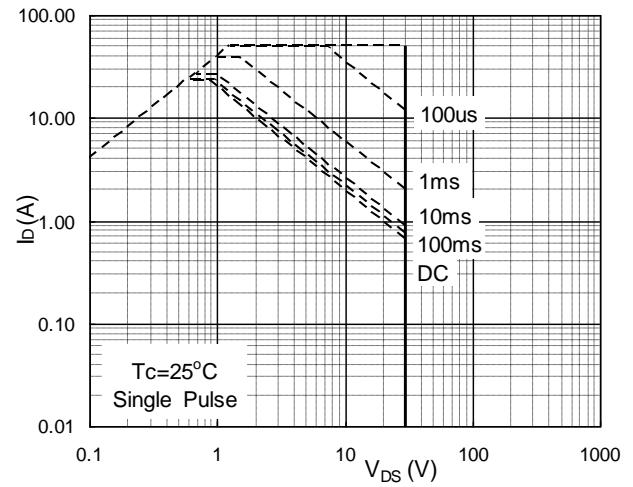
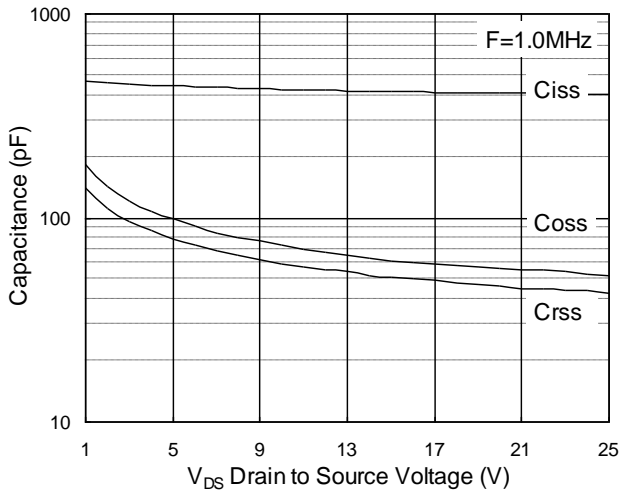
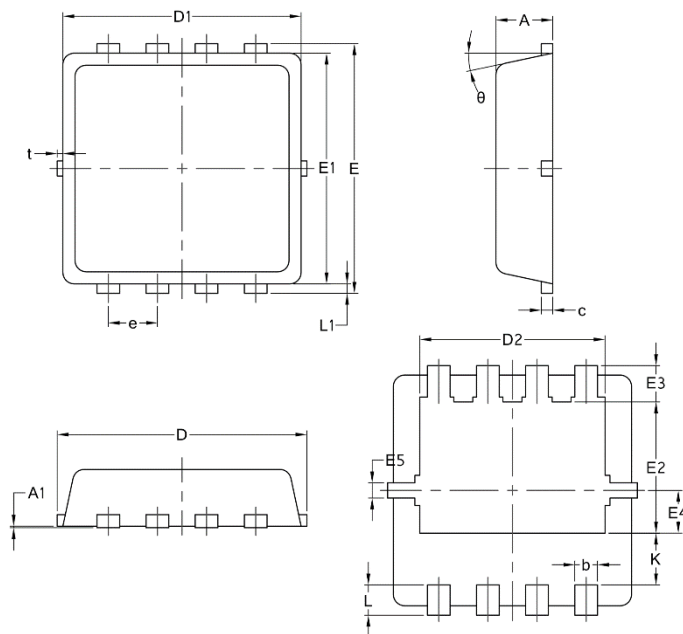


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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### Package Mechanical Data-DFN3\*3-8L-JQ Single



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14

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## 30V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2018/1/31	Initial release

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### Test Report For 30PCS (30pcs 典型測試報告)

